

MZVLB256HAHQ-00000/07  
MZVLB512HAJQ-00000/07  
MZVLB1T0HALR-00000/07  
MZVLB2T0HMLB-00000/07

# M.2 NVMe PCIe SSD specification

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(PM981)

## datasheet

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# datasheet

## Revision History

<u>Revision No.</u>	<u>History</u>	<u>Draft Date</u>	<u>Remark</u>	<u>Created by</u>	<u>Review by</u>
1.0	1. Initial issue	Aug 07, 2017	Final	K.W Shin	
1.1	1.Deleted 128GB and changed the part number of 256GB.	Sep. 28, 2017	Final	S.J Oh	Elly. Shin
1.2	1. Updates Power and performance of 256GB/2TB.	Jan.22, 2018	Final	S.J Oh	S.J Oh
1.3	1. Modifies Typos (4.2 Pin Assignments and Definition)	Apr.11, 2018	Final	S.J Oh	S.J Oh

# PM981 Series

PART NUMBER	Capacity <sup>1)</sup>	LBA <sup>2)</sup>
MZVLB256HAHQ-00000/07	256GB	500,118,192
MZVLB512HAJQ-00000/07	512GB	1,000,215,216
MZVLB1T0HALR-00000/07	1TB	2,000,409,264
MZVLB2T0HMLB-00000/07	2TB	4,000,797,360

FEATURES	Reliability Specifications
<ul style="list-style-type: none"> <li>• PCIe Gen3 8Gb/s Interface, up to 4 Lanes</li> <li>• Compliant with PCI Express Base Specification Rev. 3.0</li> <li>• Compliant with PCI Express M.2 Specification Rev. 1.1</li> <li>• Compliant with NVMe Express specification Rev. 1.2a</li> <li>• Power Saving Modes:               <ul style="list-style-type: none"> <li>- Supporting APST</li> <li>- Supporting L1.2 Mode</li> </ul> </li> <li>• Support Admin &amp; NVM Command Set</li> <li>• RoHS Compliant</li> <li>• Hardware based AES-XTS 256-bit Encryption Engine for SED</li> <li>• TCG OPAL (v2.0) Compliant for SED</li> </ul>	UBER < 1 sector per 10 <sup>15</sup> bits read MTBF 1.5 Million Hours <b>Environmental Specifications</b> Temperature Operating <sup>4</sup> 0°C to 70°C Non-operating -40°C to 85°C Humidity (non-condensing) Non-operating 5 ~ 95% Linear Shock (0.5ms duration with 1/2 sine wave) Non-operating 1,500 Gpeak Vibration Non-operating (20 ~ 2,000 Hz, Sinusoidal) 20 Gpeak

Drive Configuration	POWER SPECIFICATIONS <sup>7)</sup>
Capacity 256/512GB/1/2TB	Supply Voltage / Tolerance 3.3V ± 5%
From Factor M.2	Voltage Ripple/Noise (max.) 100mV p-p
Interface PCI Express Gen3 x4	Active <sup>5</sup> (Typ, RMS)
Bytes per Sector 512Byte	- Read 5.9W
	- Write 5.7W

Performance Specifications <sup>3)</sup>	Idle <sup>6</sup> (Typ.) 30mW
Data Transfer Rate (128KB)	L1.2 (Typ) 5mW
Sequential Read (256GB) Up to 3,000 MB/s	
(512GB) Up to 3,000 MB/s	
(1TB) Up to 3,200 MB/s	
(2TB) Up to 3,300 MB/s	
Sequential Write (256GB) Up to 1,300 MB/s	
(512GB) Up to 1,800 MB/s	
(1TB) Up to 2,400 MB/s	
(2TB) Up to 2,400 MB/s	
Data I/O Speed (4KB)	
Random Read (256GB) Up to 130K IOPS	
(512GB) Up to 270K IOPS	
(1TB) Up to 380K IOPS	
(2TB) Up to 340K IOPS	
Random Write (256GB) Up to 310K IOPS	
(512GB) Up to 420K IOPS	
(1TB) Up to 440K IOPS	
(2TB) Up to 440K IOPS	

PHYSICAL DIMENSION	
Width	22.00 ± 0.15 mm
Length	80.00 ± 0.15 mm
Height	
- Single Side	Max. 2.38 mm
Weight	Max. 9.0g

*Specifications are subject to change without notice.*

1) 1MB = 1,000,000 Bytes, 1GB = 1,000,000,000 Bytes, Unformatted Capacity. User accessible capacity may vary depending on operating environment and formatting.  
 2) 1 Sector = 512Bytes, Max. LBA represents the total user addressable sectors in LBA mode and calculated by IDEMA rule  
 3) Actual performance may vary depending on use conditions and environment. Performance measurements based on TurboWrite technology.  
 4) Measured by SMART Temperature. Proper airflow recommended.  
 5) Active power is measured on sequential write and read.  
 6) Idle Power is measured on Idle status with L1.2+APST/ASPM on.  
 7) Active/Idle/L1.2 Power are measured up to 1TB.

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## 1.0 INTRODUCTION

### 1.1 General Description

This document describes the specification of PM981 SSD which uses PCIe interface.

The PM981 is fully consist of semiconductor device and using NAND Flash Memory which has a high reliability and a high technology in a small form factor for using a SSD and supporting Peripheral Component Interconnect Express (PCIe) 3.0 interface standard up to 4 lanes shows much faster performance than previous SATA SSDs.

The PM981 provides 256GB, 512GB, 1TB and 2TB capacities. It's sequential performance is up to 3,300MB/s for read operation and 2,400MB/s for write operation by 4 lanes. It's random performance is up to 380k IOPS for read and 440k IOPS for write operation by 4 lanes. It could also provide rugged features with an extreme environment with a high MTBF.

### 1.2 Product List

[Table 1] Product Line-up

Type	Capacity	Part Number
M.2	256GB	MZVLB256HAHQ-00000/07
	512GB	MZVLB512HAJQ-00000/07
	1TB	MZVLB1T0HALR-00000/07
	2TB	MZVLB2T0HMLB-00000/07

### 1.3 Ordering Information

**M Z X X X X X X X X X X - X X X X X**  
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

**1. Memory (M)**

**2. Module Classification**  
 Z: SSD

**3. Form Factor**  
 V: PCIeM.2 (22\*80, PCIe x4)

**4. Line-Up**  
 L: Client/SV (VNAND 3bit MLC)

**5. SSD CTRL**  
 B: Phoenix

**6~8. SSD Density**  
 256: 256GB  
 512: 512GB  
 1T0: 1TB  
 2T0: 2TB

**9. NAND PKG + NAND Voltage**  
 H: BGA (LF,HF)

**10. Flash Generation**  
 M: 1st Generation  
 A: 2nd Generation

**11~12. NAND Density**  
 HQ: 1T QDP 4CE  
 JQ: 2T ODP 4CE  
 LR: 4T HDP 4CE  
 LB: 8T HDP 4CE

**13. "-"**

**14. Default**  
 "0"

**15. HW revision**  
 0: No revision

**16. Packaging type**  
 0: Bulk

**17~18. Customer**  
 00: World wide (non-SED)  
 07: World wide (SED)

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## 2.0 PRODUCT SPECIFICATION

### 2.1 Capacity

[Table 2] User Addressable Sectors

Capacity	Max LBA
256GB <sup>1)</sup>	500,118,192
512GB <sup>1)</sup>	1,000,215,216
1TB	2,000,409,264
2TB	4,000,797,360

**NOTE:**

1) Gigabyte (GB) = 1,000,000,000 Bytes, 1 Sector = 512Bytes

2) Max. LBA shown in Table 1 represents the total user addressable sectors in LBA mode and calculated by IDEMA rule.

### 2.2 Performance<sup>1)</sup>

[Table 3] Drive Performance

**Gen3**

Parameter	Unit	Queue Depth	256GB	512GB	1TB	2TB
Sequential Read <sup>2)</sup> (Up to)	MB/s	QD = 32	3,000	3,000	3,200	3,300
Sequential Write <sup>2)</sup> (Up to)	MB/s	QD = 32	1,300	1,800	2,400	2,400
Random Read <sup>3)</sup> (Up to)	IOPS	QD = 1	11K	12K	12K	11K
	IOPS	QD = 32	130K	270K	380K	340K
Random Write <sup>3)</sup> (Up to)	IOPS	QD = 1	50K	50K	50K	50K
	IOPS	QD = 32	310K	420K	440K	440K

**NOTE:**

1) Performance measured using CDM 5.0.2 on Windows 10 64bit. Actual performance may vary depending on use conditions and environment.

2) Sequential performance measured using 128KB data size. (QD=32 by Thread=1)

3) Random performance measured using 4KB data size. (QD=32 by Thread 4, QD=1 by Thread 1)

4) Performance measurements based on TurboWrite technology

### 2.3 Power

[Table 4] Maximum Ratings

Parameter	Specifications	
Supply Voltage	Allowable voltage	3.3V ± 5%
	Allowable noise/ripple	100mV p-p or less

[Table 5] Power Consumption for M.2 (3.3V Supply)

Parameter	Specifications		
Power Consumption <sup>4)</sup>	Active <sup>1)</sup> (Typical, RMS)	Read	5.9W
		Write	5.7W
	Idle <sup>2)</sup> (Typical)		30mW
	L1.2 <sup>3)</sup> (Typical)		5mW

**NOTE:**

1) Active power is measured on sequential write and read.

2) Idle Power is measured on Idle status with L1.2+APST/ASPM on.

3) If L1.2 time logging option is enabled, L1.2 Power could be 5mW.

4) Active/Idle/L1.2 Power are measured up to 1TB.

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## 2.4 Reliability

This chapter provides the information for the reliability features of the SSD.

### 2.4.1 MTBF

MTBF is Mean Time Between Failure, and is the predicted elapsed time between inherent failures of a system during operation. As same word, AFR (annual failure ratio) is 0.4%. MTBF can be calculated as the arithmetic average time between failures of a system.

[Table 6] MTBF Specifications

Capacity	MTBF
256GB	1,500,000 Hours
512GB	
1TB	
2TB	

### 2.4.2 UBER

UBER is Uncorrectable Bit Error Rate.

[Table 7] UBER Specifications

Parameter	Specification
UBER	< 1 sector per 10 <sup>15</sup> bits read

## 2.5 Environmental Specification

[Table 8] Temperature, Humidity, Shock, Vibration

Parameter	Mode	Specification
Temperature	Operating <sup>1)</sup>	0°C to 70°C
	Non-operating	-40°C to 85°C
Humidity <sup>2)</sup>	Non-operating	5% to 95%
Shock <sup>3)</sup>	Non-operating	1500G
Vibration <sup>4)</sup>	Non-operating	20G

**NOTE:**

- 1) Temperature is measured by SMART Temperature. Proper airflow recommended
- 2) Humidity is measured in non-condensing
- 3) Test condition for shock: 0.5ms duration with half sine wave
- 4) Test condition for vibration: 20Hz to 2000Hz

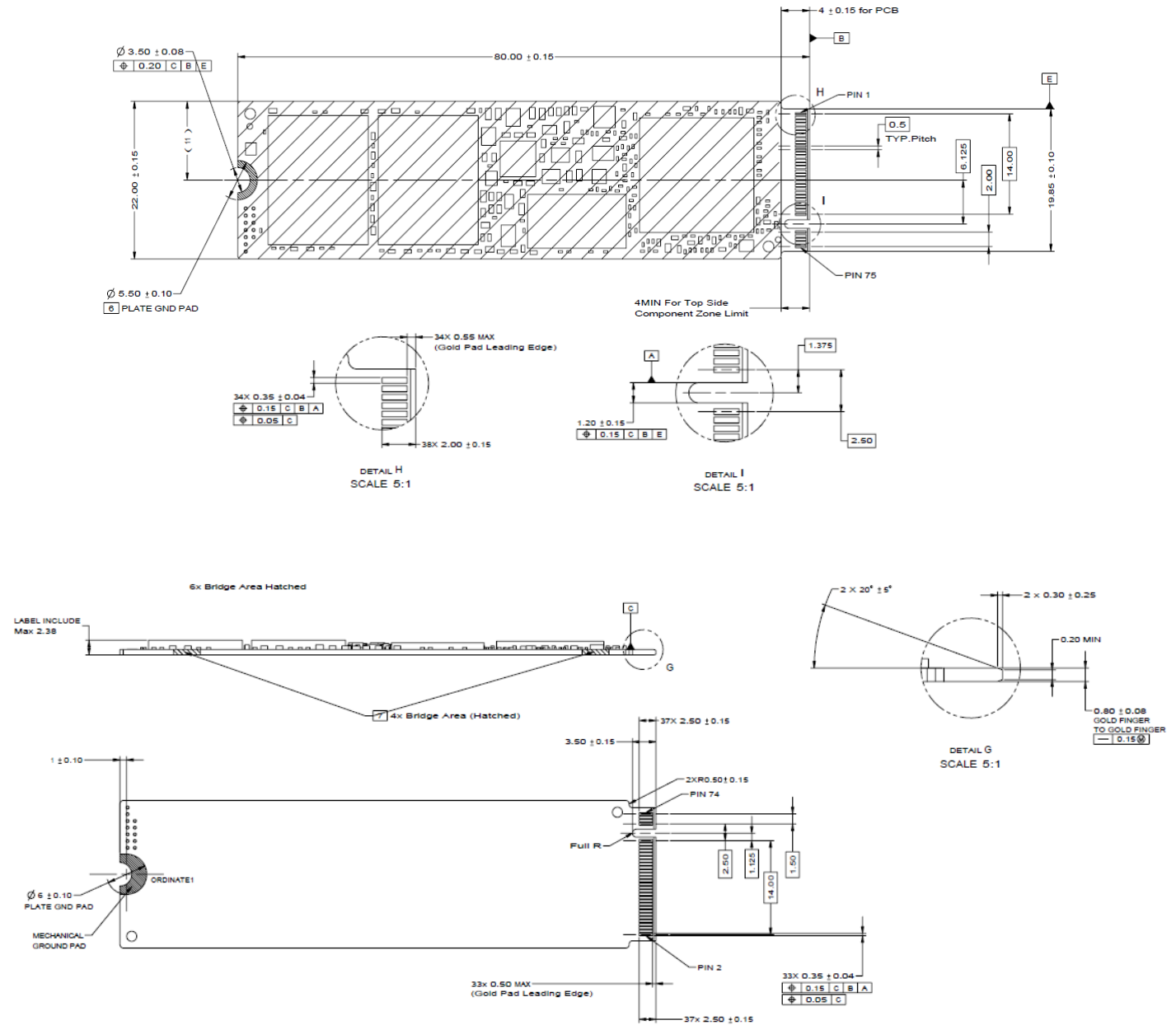
### 3.0 MECHANICAL SPECIFICATION

#### 3.1 Physical dimensions and Weight

[Table 9] Physical dimensions and Weight

Parameter		Value
Width		22.00 ± 0.15 mm
Length		80.00 ± 0.15 mm
Thickness		Max. 2.38 mm
Weight	256/512GB/1/2TB	Max 9.0g

#### 3.2 Form Factor



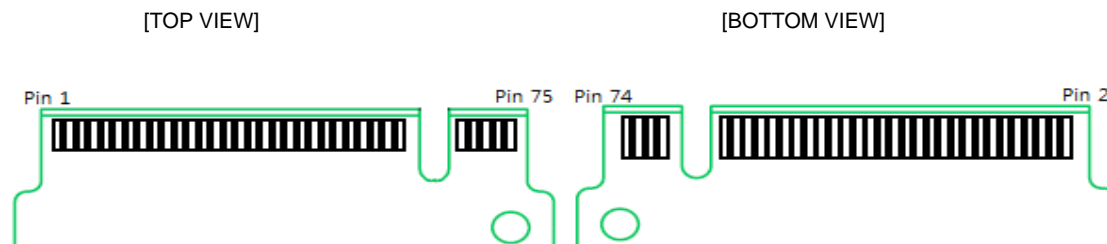
[Figure 1] M.2 Package

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## 4.0 INTERFACE SPECIFICATION

### 4.1 Connector Dimension and Pin Location



[Figure 2] M.2 Signal and Power pins

### 4.2 Pin Assignments and Definition

[Table 10] Signal Assignments

Pin#	Assignment	Description	Pin#	Assignment	Description
1	GND	Return current path	2	3.3V	3.3V source
3	GND	Return current path	4	3.3V	3.3V source
5	PETn3	PCIe TX	6	N/C	N/C
7	PETp3	PCIe TX	8	N/C	N/C
9	GND	Return current path	10	LED1#	Device Active Signal (Refer to [Table 11])
11	PERn3	PCIe Rx	12	3.3V	3.3V source
13	PERp3	PCIe Rx	14	3.3V	3.3V source
15	GND	Return current path	16	3.3V	3.3V source
17	PETn2	PCIe TX	18	3.3V	3.3V source
19	PETp2	PCIe TX	20	N/C	N/C
21	GND	Return current path	22	N/C	N/C
23	PERn2	PCIe Rx	24	N/C	N/C
25	PERp2	PCIe Rx	26	N/C	N/C
27	GND	Return current path	28	N/C	N/C
29	PETn1	PCIe TX	30	N/C	N/C
31	PETp1	PCIe TX	32	N/C	N/C
33	GND	Return current path	34	N/C	N/C
35	PERn1	PCIe Rx	36	N/C	N/C
37	PERp1	PCIe Rx	38	N/C	N/C
39	GND	Return current path	40	SMB_CLK (I/O) <sup>2)</sup>	DNU (Do Not Use)
41	PETn0	PCIe TX	42	SMB_DATA (I/O) <sup>2)</sup>	DNU (Do Not Use)
43	PETp0	PCIe TX	44	ALERT# (O) <sup>1)</sup>	DNU (Do Not Use)
45	GND	Return current path	46	N/C	N/C
47	PERn0	PCIe Rx	48	N/C	N/C
49	PERp0	PCIe Rx	50	PERST#	PCIe Reset
51	GND	Return current path	52	CLKREQ#	PCIe Device Clock Request
53	REFCLKN	PCIe Reference Clock	54	PEWake#	N/C
55	REFCLKP	PCIe Reference Clock	56	Reserved for MFG_-Data	N/C
57	GND	Return current path	58	Reserved for MFG_-CLOCK	N/C
67	N/C	N/C	68	SUSCLK	DNU (Do Not Use)
69	PEDET	N/C	70	3.3V	3.3V source
71	GND	Return current path	72	3.3V	3.3V source

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73	GND	Return current path	74	3.3V	3.3V source
75	GND	Return current path			

**NOTE:**

- 1) Not support: open drain with pull-up on platform (1.8V), active low.
- 2) Not support: open drain with pull-up on platform (1.8V).

**[Table 11] Simple Indicator Protocol for SSD LED States (Optional)**

ASPM <sup>1)</sup>		LED Status
Active State (Host send CMD to SSD)		Blinking
Idle	Low Power standby	OFF
State	Deep Sleep Power savings	OFF

**NOTE:**

- 1) ASPM (Active State Power Management)

## 5.0 PCI and NVM Express registers

### 5.1 PCI Express Registers

#### 5.1.1 PCI Register Summary

[Table 12] PCI Register Summary

Start Address	End Address	Name	Type
00h	3Fh	PCI Header	PCI Configuration Header Space
40h	47h	PCI Power Management Capability	PCI Capability
50h	67h	MSI Capability	PCI Capability
70h	A3h	PCI Express Capability	PCI Capability
B0h	BBh	MSI-X Capability	PCI Capability
100h	12Bh	Advanced Error Reporting Capability	PCI Extended Capability
148h	153h	Device Serial Number Capability	PCI Extended Capability
158h	167h	Power Budgeting Capability	PCI Extended Capability
168h	17Bh	Secondary PCI Express Capability	PCI Extended Capability
188h	18Fh	Latency Tolerance Reporting Capability	PCI Extended Capability
190h	19Fh	L1 Substates Capability	PCI Extended Capability

#### 5.1.2 PCI Configuration Header Space Registers Detail

##### 5.1.2.1 PCI Configuration Header Space Registers

[Table 13] PCI Header Space Summary

Start Address	End Address	Symbol	Description
00h	03h	IDTF	Identifiers
04h	05h	CMD	Command Register
06h	07h	STS	Status Register
08h	08h	REVID	Revision ID
09h	0Bh	CC	Class Codes
0Ch	0Ch	CLS	Cache Line Size
0Dh	0Dh	MLT	Master Latency Timer
0Eh	0Eh	HTYPE	Header Type
0Fh	0Fh	BIST	Built in Self Test
10h	13h	MLBAR (BAR0)	Memory Register Base Address (lower 32-bit)
14h	17h	MUBAR (BAR1)	Memory Register Base Address (upper 32-bit)
18h	1Bh	IDBAR (BAR2)	Reserved
1Ch	1Fh	BAR3	Reserved
20h	23h	BAR4	Reserved
24h	27h	BAR5	Reserved
28h	2Bh	CCPTR	CardBus CIS Pointer
2Ch	2Fh	SS	Subsystem Identifiers
30h	33h	EXPROM	Expansion ROM Base Address
34h	34h	CAP	Capabilities Pointer
35h	3Bh	R	Reserved
3Ch	3Dh	INTR	Interrupt Information
3Eh	3Eh	MGNT	Minimum Grant
3Fh	3Fh	MLAT	Maximum Latency

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[Table 14] Identifier Register

Bits	Type	Default Value	Description
31:16	RO	A808h	Device ID
0:15	RO	144Dh	Vendor ID

[Table 15] Command Register

Bits	Type	Default Value	Description
15:11	RO	0h	Reserved
10	RW	0	Interrupt Disable
9	RO	0	Fast Back-to-Back Enable (N/A)
8	RW	0	SERR# Enable
7	RO	0	IDSEL Stepping/Wait Cycle Control (N/A)
6	RW	0	Parity Error Response Enable
5	RO	0	VGA Palette Snooping Enable (N/A)
4	RO	0	Memory Write and Invalidate Enable (N/A)
3	RO	0	Special Cycle Enable (N/A)
2	RW	0	Bus Master Enable
1	RW	0	Memory Space Enable
0	RW	0	I/O Space Enable

[Table 16] Status Register

Bits	Type	Default Value	Description
15	RW1C	0	Detected Parity Error
14	RW1C	0	Signaled System Error
13	RW1C	0	Received Master Abort
12	RW1C	0	Received Target Abort
11	RW1C	0	Signaled Target Abort (N/A)
10:9	RO	0h	DEVSEL Timing (N/A)
8	RW1C	0	Master Data Parity Error Detected
7	RO	0	Fast Back-to-Back Transaction Capable (N/A)
6	RO	0	Reserved
5	RO	0	66MHz Capable (N/A)
4	RO	1	Capabilities List
3	RO	0	Interrupt Status
2:1	RO	0h	Reserved
0	RO	0	Reserved

[Table 17] Revision ID Register

Bits	Type	Default Value	Description
7:0	RO	00h	Controller Hardware Revision ID

[Table 18] Class Code Register

Bits	Type	Default Value	Description
23:16	RO	1h	Base Class Code
15:8	RO	8h	Sub Class Code
7:0	RO	2h	Programming Interface

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[Table 19] Cache Line Size Register

Bits	Type	Default Value	Description
7:0	RW	0h	Cache Line Size (N/A)

[Table 20] Master Latency Timer Register

Bits	Type	Default Value	Description
7:0	RO	0h	Master Latency Timer (N/A)

[Table 21] Header Type Register

Bits	Type	Default Value	Description
7	RO	0	Multi-Function Device (N/A)
6:0	RO	0h	Reserved

[Table 22] Built In Self Test Register

Bits	Type	Default Value	Description
7:0	RO	0h	Built In Self Test (N/A)

[Table 23] Memory Register Base Address Lower 32-bits (BAR0) Register

Bits	Type	Default Value	Description
31:14	RW	0h	Base Address
13:4	RO	0h	Reserved
3	RO	0	Pre-Fetchable
2:1	RO	2h	Address Type (64-bit)
0	RO	0	Memory Space Indicator (MEMSI)

[Table 24] Memory Register Base Address Upper 32-bits (BAR1)

Bits	Type	Default Value	Description
31:0	RO	0h	Base Address

[Table 25] Index/Data Pair Register Base Address (BAR2) Register

Bits	Type	Default Value	Description
31:0	RO	0h	N/A

[Table 26] BAR3 Register

Bits	Type	Default Value	Description
31:0	RO	0h	N/A

[Table 27] Vendor Specific BAR4 Register

Bits	Type	Default Value	Description
31:0	RO	0h	N/A

[Table 28] Vendor Specific BAR5 Register

Bits	Type	Default Value	Description
31:0	RO	0h	N/A

[Table 29] Cardbus CIS Pointer Register

Bits	Type	Default Value	Description
31:0	RO	0h	N/A

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[Table 30] Subsystem Identifier Register

Bits	Type	Default Value	Description
31:16	RO	A801h	Subsystem ID
15:0	RO	144Dh	Subsystem Vendor ID

[Table 31] Expansion ROM Register

Bits	Type	Default Value	Description
31:17	RW	0h	Expansion ROM Base Address
16:1	RO	0h	Reserved
0	RW	0	Expansion ROM Enable/Disable

[Table 32] Capabilities Pointer Register

Bits	Type	Default Value	Description
7:0	RO	40h	Capability Pointer

[Table 33] Interrupt Information Register

Bits	Type	Default Value	Description
15:8	RO	01h	Interrupt Pin
7:0	RW	FFh	Interrupt Line

[Table 34] Minimum Grant Register

Bits	Type	Default Value	Description
7:0	RO	0h	Minimum Grant

[Table 35] Maximum Latency Register

Bits	Type	Default Value	Description
7:0	RO	0h	Maximum Latency

## 5.1.3 PCI Capability Registers Detail

### 5.1.3.1 PCI Power Management Capability

[Table 36] PCI Power Management Capability Summary

Start Address	End Address	Symbol	Description
40h	40h	PCIPM_ID	PCI Power Management Capability ID
41h	41h	NEXTCAP	Next Capability Pointer
42h	43h	PCIPM_CAP	PCI Power Management Capabilities
44h	45h	PCIPM_CS	PCI Power Management Control and Status
46h	46h	PCIPM_CSR_BSE	PMCSR_BSE Bridge Extensions
47h	47h	PCIEPM_DATA	Data

[Table 37] PCI Power Management Capability ID Register

Bits	Type	Default Value	Description
15:8	RO	50h	Next Capability
7:0	RO	1h	Capability ID

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[Table 38] PCI Power Management Capability Register

Bits	Type	Default Value	Description
15:11	RO	0h	PME Support (N/A)
10	RO	0	D2 Support (N/A)
9	RO	0	D1 Support (N/A)
8:6	RO	0h	AUX Current (N/A)
5	RO	0	Device Specific Initialization (N/A)
4	RsvdP	0	Reserved
3	RO	0	PME Clock (N/A)
2:0	RO	3h	Version (Support for PCI Bus Power Management Interface Spec R1.2)

[Table 39] PCI Power Management Control and Status Register

Bits	Type	Default Value	Description
31:24	RsvdP	0h	Data register (N/A)
23	RO	0	Bus Power/Clock Enable (N/A)
22	RO	0	B2, B3 support (N/A)
21:16	RsvdP	0h	Reserved
15	RO	0	PME_Status (N/A)
14:13	RO	0h	Data Scale (N/A)
12:9	RO	0h	Data Select (N/A)
8	RWS	0	PME enable (N/A)
7:4	RsvdP	0h	Reserved
3	RO	1	No Soft Reset
2	RsvdP	0	Reserved
1:0	RW	0h	Power State

## 5.1.3.2 Message Signaled Interrupt (MSI) Capability

[Table 40] Message Signaled Interrupt Capability Summary

Start Address	End Address	Symbol	Description
50h	51h	MSI_ID	Message Signaled Interrupt Capability ID
52h	53h	MSI_MC	Message Signaled Interrupt Message Control
54h	57h	MSI_MA	Message Signaled Interrupt Message Address
58h	5Bh	MSI_MUA	Message Signaled Interrupt Upper Address
5Ch	5Dh	MSI_MDATA	Message Signaled Interrupt Message Data
60h	63h	MSI_MMASK	Message Signaled Interrupt Mask Bits
64h	67h	MSI_MPEND	Message Signaled Interrupt Pending Bits

[Table 41] Message Signaled Interrupt Capability ID Register

Bits	Type	Default Value	Description
15:8	RO	70h	Next Capability
7:0	RO	05h	Capability ID

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

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[Table 42] Message Signaled Interrupt Control Register

Bits	Type	Default Value	Description
15:9	RsvdP	0h	Reserved
8	RO	0	Per Vector Masking Capable (N/A)
7	RO	1h	64-bit Address Capable
6:4	RW	0h	Multiple Message Enable
3:1	RO	5h	Multiple Message Capable
0	RW	0	MSI Enable

[Table 43] Message Signaled Interrupt Address Register

Bits	Type	Default Value	Description
31:2	RW	0h	Address
1:0	RO	0h	Reserved

[Table 44] Message Signaled Interrupt Upper Address Register

Bits	Type	Default Value	Description
31:0	RW	0h	Upper Address

[Table 45] Message Signaled Interrupt Message Data Register

Bits	Type	Default Value	Description
31:16	RsvdP	0h	Reserved
0:15	RW	0h	Data

[Table 46] Message Signaled Interrupt Mask Bits Register

Bits	Type	Default Value	Description
31:0	RW	0h	Mask Bits (N/A)

[Table 47] Message Signaled Interrupt Pending Bits Register

Bits	Type	Default Value	Description
31:0	RO	0h	Pending Bits



5.1.3.3 PCI Express Capability

[Table 48] PCI Express Capability Summary

Start Address	End Address	Symbol	Description
70h	71h	PCIE_ID	PCI Express Capability ID
72h	73h	PCIE_CAP	PCI Express Capabilities
74h	77h	PCIE_DCAP	PCI Express Device Capabilities
78h	79h	PCIE_DC	PCI Express Device Control
7Ah	7Bh	PCIE_DS	PCI Express Device Status
7Ch	7Fh	PCIE_LCAP	PCI Express Link Capabilities
80h	81h	PCIE_LC	PCI Express Link Control
82h	83h	PCIE_LS	PCI Express Link Status
94h	97h	PCIE_DCAP2	PCI Express Device Capabilities 2
98h	99h	PCIE_DC2	PCI Express Device Control 2
9Ah	9Bh	PCIE_DS2	PCI Express Device Status 2
9Ch	9Fh	PCIE_LCAP2	PCI Express Link Capabilities 2
A0h	A1h	PCIE_LC2	PCI Express Link Control 2
A2h	A3h	PCIE_LS2	PCI Express Link Status 2

[Table 49] PCI Express Capability ID Register

Bits	Type	Default Value	Description
15:8	RO	B0h	Next Pointer
7:0	RO	10h	Capability ID

[Table 50] PCI Express Capabilities Register

Bits	Type	Default Value	Description
15:14	RsvdP	0h	Reserved
13:9	RO	0h	Interrupt Message Number
8	Hwlnit	0	Slot Implementation (N/A)
7:4	RO	0h	Device/Port Type
3:0	RO	2h	Capability Version

[Table 51] PCI Express Device Capabilities Register

Bits	Type	Default Value	Description
31:29	RsvdP	0h	Reserved
28	RO	1	Function Level Reset Capability
27:26	RO	0h	Captured Slot Power Limit Scale
25:18	RO	0h	Captured Slot Power Limit Value
17:16	RsvdP	0h	Reserved
15	RO	1	Role-based Error Reporting
14:12	RO	0h	Reserved
11:9	RO	7h	Endpoint L1 Acceptable Latency
8:6	RO	7h	Endpoint L0 Acceptable Latency
5	RO	0	Extended Tag Field Supported
4:3	RO	0h	Phantom Functions Supported
2:0	RO	1h	Max Payload Size Supported

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

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[Table 52] PCI Express Device Control Register

Bits	Type	Default Value	Description
15	RW	0	Initiate Function Level Reset
14:12	RW	2h	Max Read Request Size
11	RW	1	Enable No Snoop
10	RWS	0	Aux Power PM Enable (N/A)
9	RW	0	Phantom Functions Enable (N/A)
8	RW	0	Extended Tag Enable
7:5	RW	0h	Max Payload Size
4	RW	1	Enable Relaxed Ordering
3	RW	0	Unsupported Request Reporting Enable
2	RW	0	Fatal Error Reporting Enable
1	RW	0	Non-Fatal Error Reporting Enable
0	RW	0	Correctable Error Reporting Enable

[Table 53] PCI Express Device Status Register

Bits	Type	Default Value	Description
15:6	RsvdZ	0h	Reserved
5	RO	0	Transactions Pending
4	RO	0	Aux Power Detected
3	RW1C	0	Unsupported Request Detected
2	RW1C	0	Fatal Error Detected
1	RW1C	0	Non-Fatal Error Detected
0	RW1C	0	Correctable Error Detected

[Table 54] PCI Express Link Capabilities Register

Bits	Type	Default Value	Description
31:24	HwInit	0h (Port 0)	Port Number
23	RsvdP	0	Reserved
22	HwInit	1	ASPM Optionality Compliance
21	RO	0	Link Bandwidth Notification Capability (N/A)
20	RO	0	Data Link Layer Link Active Reporting Capable (N/A)
19	RO	0	Surprise Down Error Reporting Capable (N/A)
18	RO	1	Clock Power Management
17:15	RO	6h	L1 Exit Latency
14:12	RO	7h	L0s Exit Latency
11:10	RO	2h	Active State Power Management Support
9:4	RO	4h (x4 link)	Maximum Link Width
3:0	RO	3h	Max Link Speeds

[Table 55] PCI Express Link Control Register

Bits	Type	Default Value	Description
15:14	RW/RsvdP	0h	Reserved
13:12	RsvdP	0h	Reserved
11	RsvdP	0	Link Autonomous Bandwidth Interrupt Enable (N/A)
10	RsvdP	0	Link Bandwidth Management Interrupt Enable (N/A)
9	RW	0	Hardware Autonomous Width Disable

**IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.**

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8	RW	0	Enable Clock Power Management
7	RW	0	Extended Sync
6	RW	0	Common Clock Configuration
5	RsvdP	0	Retrain Link (N/A)
4	RsvdP	0	Link Disable (N/A)
3	RW	0	Read Completion Boundary (N/A)
2	RsvdP	0	Reserved
1:0	RW	0h	Active State Power Management Control

[Table 56] PCI Express Link Status Register

Bits	Type	Default Value	Description
15	RW1C	0h	Link Autonomous Bandwidth Status (N/A)
14	RW1C	0	Link Bandwidth Management Status (N/A)
13	RO	0	Data Link Layer Link Active
12	Hwlnit	1	Slot Clock Configuration
11	RO	0	Link Training (N/A)
10	RO	0	Reserved
9:4	RO	1h	Negotiated Link Width
3:0	RO	1h	Current Link Speed

[Table 57] PCI Express Device Capabilities 2 Register

Bits	Type	Default Value	Description
31	Hwlnit	0	Reserved
30:24	RsvdP	0h	Reserved
23:22	Hwlnit	0h	Max End-End TLP Prefixes (N/A)
21	Hwlnit	0	End-End TLP Prefix Supported (N/A)
20	RO	0	Extended Format Field Supported (N/A)
19:18	Hwlnit	0h	OBFF Supported (N/A)
17:16	RsvdP	0h	Reserved
15:14	Hwlnit	0h	LN System CLS (N/A)
13:12	RO	0h	TPH Completer Supported (N/A)
11	RO	1	Latency Tolerance Reporting Supported
10	Hwlnit	0	No RO-enabled PR-PR Passing (N/A)
9	RO	0	128-bit CAS Completer Supported (N/A)
8	RO	0	64-bit Atomic Op Completer Supported (N/A)
7	RO	0	32-bit Atomic Op Completer Supported (N/A)
6	RO	0	Atomic Op Routing Supported (N/A)
5	RO	0	ARI Forwarding Supported (N/A)
4	RO	1	Completion Timeout Disable Supported
3:0	Hwlnit	Fh	Completion Timeout Ranges Supported

[Table 58] PCI Express Device Control 2 Register

Bits	Type	Default Value	Description
15	RsvdP	0	End-to-end TLP Prefix Blocking (N/A)
14:13	RW/RsvdP	0h	OBFF Enable (N/A)
12:11	RsvdP	0h	Reserved
10	RW	0	Latency Tolerance Reporting Mechanism Enable
9	RW	0	IDO Completion Enable (N/A)

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

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8	RW	0	IDO Request Enable (N/A)
7	RW	0	AtomicOp Egress Blocking (N/A)
6	RW	0	AtomicOp Requester Enable (N/A)
5	RW	0	ARI Forwarding Enable (N/A)
4	RW	0	Completion Timeout Disable
3:0	RW	0h	Completion Timeout Value

[Table 59] PCI Express Device Status 2 Register

Bits	Type	Default Value	Description
15:0	RsvdZ	0h	Reserved

[Table 60] PCI Express Link Capabilities 2 Register

Bits	Type	Default Value	Description
31	RO	0	Reserved
30:24	RsvdP	0h	Reserved
23	HWinit	0	Reserved
22:16	HWinit	0h	Lower SKP OS Reception Supported Speed Vector (N/A)
15:9	HWinit	0h	Lower SKP OS Generation Supported Speed Vector (N/A)
8	RO	0	Cross-Link Supported (N/A)
7:1	RO	7h	Supported Speeds Vector
0	RsvdP	0	Reserved

[Table 61] PCI Express Link Control 2 Register

Bits	Type	Default Value	Description
15:12	RWS/RsvdP	0h	Compliance De-emphasis
11	RWS/RsvdP	0	Compliance SOS
10	RWS/RsvdP	0	Enter Modified Compliance
9:7	RWS/RsvdP	0h	Transmit Margin
6	Hwinit	0	Selectable De-Emphasis (N/A)
5	RWS/RsvdP	0	Hardware Autonomous Speed Disable
4	RWS/RsvdP	0	Enter Compliance
3:0	RWS/RsvdP	3h	Target Link Speed

[Table 62] PCI Express Link Status 2 Register

Bits	Type	Default Value	Description
15:6	RsvdP	0h	Reserved
5	RW1CS	0	Link Equalization Request 8.0GT/s
4	ROS	0	Equalization 8.0GT/s Phase 3 Successful
3	ROS	0	Equalization 8.0GT/s Phase 2 Successful
2	ROS	0	Equalization 8.0GT/s Phase 1 Successful
1	ROS	0	Equalization 8.0GT/s Complete
0	RO	1	Current De-Emphasis

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

5.1.3.4 MSI-X Capability

[Table 63] MSI-X Capability Summary

Start Address	End Address	Symbol	Description
B0h	B1h	MSIX_ID	MSI-X Capability ID
B2h	B3h	MSIX_CAP	MSI-X Message Control
B4h	B7h	MSIX_TBL	MSI-X Table Offset and Table BIR
B8h	BBh	MSIX_PBA	MSI-X PBA Offset and PBA BIR

[Table 64] MSI-X Identifier Register

Bits	Type	Default Value	Description
15:8	RO	00h	Next Capability
7:0	RO	11h	Capability ID

[Table 65] MSI-X Control Register

Bits	Type	Default Value	Description
15	RW	0	MSI-X Enable
14	RW	0	Function Mask
13:11	RsvdP	0h	Reserved
10:0	RO	20h	Table Size

[Table 66] MSI-X Table Offset Register

Bits	Type	Default Value	Description
31:3	RO	600h	Table Offset
2:0	RO	0h	Table BIR

[Table 67] MSI-X Pending Bit Array Offset Register

Bits	Type	Default Value	Description
31:3	RO	400h	Pending Bit Array Offset
2:0	RO	0h	Pending Bit Array BIR

5.1.4 PCI Extended Capability Details

5.1.4.1 Advanced Error Reporting Registers

[Table 68] Advanced Error Reporting Capability Summary

Start Address	End Address	Symbol	Description
100h	103h	AER_ID	AER Capability ID
104h	107h	AER_UCES	AER Uncorrectable Error Status
108h	10Bh	AER_UCEM	AER Uncorrectable Error Mask
10Ch	10Fh	AER_UCESEV	AER Uncorrectable Error Severity
110h	113h	AER_CES	AER Correctable Error Status
114h	117h	AER_CEM	AER Correctable Error Mask
118h	11Bh	AER_CC	AER Advanced Error Capabilities and Control
11Ch	12Bh	AER_HL	AER Header Log

[Table 69] AER Capability ID Register

Bits	Type	Default Value	Description
31:20	RO	148h	Next Pointer (Points to Secondary PCI Express Extended Capability Header Offset)
19:16	RO	2h	Capability Version
15:0	RO	1h	Capability ID

[Table 70] AER Uncorrectable Error Status Register

Bits	Type	Default Value	Description
31:27	RsvdZ	0h	Reserved
26	RW1CS	0	Poisoned TLP Egress Blocked Status (N/A)
25	RW1CS	0	TLP Prefix Blocked Error Status (N/A)
24	RW1CS	0	Atomic Op Egress Blocked Status (N/A)
23	RW1CS	0	MC Blocked TLP Status (N/A)
22	RW1CS	0	Uncorrectable Internal Error Status
21	RW1CS	0	ACS Violation Status (N/A)
20	RW1CS	0	Unsupported Request Error Status
19	RW1CS	0	ECRC Error Status
18	RW1CS	0	Malformed TLP Status
17	RW1CS	0	Receiver Overflow Status
16	RW1CS	0	Unexpected Completion Status
15	RW1CS	0	Completer Abort Status
14	RW1CS	0	Completion Timeout Status
13	RW1CS	0	Flow Control Protocol Error Status
12	RW1CS	0	Poisoned TLP Status
11:6	RsvdZ	0h	Reserved
5	RW1CS	0	Surprise Down Error Status (N/A)
4	RW1CS	0	Data Link Protocol Error Status
3:1	RsvdZ	0h	Reserved
0	Undefined	0	Undefined

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

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[Table 71] AER Uncorrectable Error Mask Register

Bits	Type	Default Value	Description
31:27	RsvdZ	0h	Reserved
26	RWS	0	Poisoned TLP Egress Blocked Mask (N/A)
25	RWS	0	TLP Prefix Blocked Error Mask (N/A)
24	RWS	0	Atomic Op Egress Blocked Mask (N/A)
23	RWS	0	MC Blocked TLP Mask (N/A)
22	RWS	1	Uncorrectable Internal Error Mask
21	RWS	0	ACS Violation Mask (N/A)
20	RWS	0	Unsupported Request Error Mask
19	RWS	0	ECRC Error Mask
18	RWS	0	Malformed TLP Mask
17	RWS	0	Receiver Overflow Mask
16	RWS	0	Unexpected Completion Mask
15	RWS	0	Completer Abort Mask
14	RWS	0	Completion Timeout Mask
13	RWS	0	Flow Control Protocol Error Mask
12	RWS	0	Poisoned TLP Mask
11:6	RsvdZ	0h	Reserved
5	RWS	0	Surprise Down Error Mask (N/A)
4	RWS	0	Data Link Protocol Error Mask
3:1	RsvdZ	0h	Reserved
0	Undefined	0	Undefined

[Table 72] AER Uncorrectable Error Severity Register

Bits	Type	Default Value	Description
31:27	RsvdP	0h	Reserved
26	RWS	0	Poisoned TLP Egress Blocked Severity (N/A)
25	RWS	0	TLP Prefix Blocked Error Severity (N/A)
24	RWS	0	Atomic Op Egress Blocked Severity (N/A)
23	RWS	0	MC Blocked TLP Severity (N/A)
22	RWS	1	Uncorrectable Internal Error Severity
21	RWS	0	ACS Violation Severity (N/A)
20	RWS	0	Unsupported Request Error Severity
19	RWS	0	ECRC Error Severity
18	RWS	1	Malformed TLP Severity
17	RWS	1	Receiver Overflow Severity
16	RWS	0	Unexpected Completion Severity
15	RWS	0	Completer Abort Severity
14	RWS	0	Completion Timeout Severity
13	RWS	1	Flow Control Protocol Error Severity
12	RWS	0	Poisoned TLP Severity
11:6	RsvdP	0h	Reserved
5	RWS	1	Surprise Down Error Severity (N/A)
4	RWS	1	Data Link Protocol Error Severity
3:1	RsvdP	0h	Reserved
0	Undefined	0	Undefined

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

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[Table 73] AER Correctable Error Status Register

Bits	Type	Default Value	Description
31:16	RsvdZ	0h	Reserved
15	RW1CS	0	Header Log Overflow Status
14	RW1CS	0	Corrected Internal Error Status
13	RW1CS	0	Advisory Non-Fatal Error Status
12	RW1CS	0	Replay Timer Timeout Status
11:9	RsvdZ	0h	Reserved
8	RW1CS	0	Replay Number Rollover Status
7	RW1CS	0	Bad DLLP Status
6	RW1CS	0	Bad TLP Status
5:1	RsvdZ	0h	Reserved
0	RW1CS	0	Received Error Status

[Table 74] AER Correctable Error Mask Register

Bits	Type	Default Value	Description
31:16	RsvdP	0h	Reserved
15	RWS	1	Header Log Overflow Mask
14	RWS	1	Corrected Internal Error Mask
13	RWS	1	Advisory Non-Fatal Error Mask
12	RWS	0	Replay Timer Timeout Mask
11:9	RsvdP	0h	Reserved
8	RWS	0	Replay Number Rollover Mask
7	RWS	0	Bad DLLP Mask
6	RWS	0	Bad TLP Mask
5:1	RsvdP	0h	Reserved
0	RWS	0	Received Error Mask

[Table 75] AER Capabilities and Control Register

Bits	Type	Default Value	Description
31:13	RsvdP	0h	Reserved
12	RO	0	Completion Timeout Prefix/Header Log Capable (N/A)
11	ROS	0	TLP Prefix Log Present (N/A)
10	RWS	0	Multiple Header Recording Enable
9	RO	1	Multiple Header Recording Capable
8	RWS	0	ECRC Check Enable
7	RO	1	ECRC Check Capable
6	RWS	0	ECRC Generation Enable
5	RO	1	ECRC Generation Capable
4:0	ROS	0h	First Error Pointer

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.



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[Table 76] AER Header Log Register

Bits	Type	Default Value	Description
127:120	ROS	0h	Header Byte 0
119:112	ROS	0h	Header Byte 1
111:104	ROS	0h	Header Byte 2
103:96	ROS	0h	Header Byte 3
95:88	ROS	0h	Header Byte 4
87:80	ROS	0h	Header Byte 5
79:72	ROS	0h	Header Byte 6
71:64	ROS	0h	Header Byte 7
63:56	ROS	0h	Header Byte 8
55:48	ROS	0h	Header Byte 9
47:40	ROS	0h	Header Byte 10
39:32	ROS	0h	Header Byte 11
31:24	ROS	0h	Header Byte 12
23:16	ROS	0h	Header Byte 13
15:8	ROS	0h	Header Byte 14
7:0	ROS	0h	Header Byte 15

## 5.1.4.2 Device Serial Number Capability

[Table 77] Device Serial Number Capability Register Summary

Start Address	End Address	Symbol	Description
148h	14Bh	DSN_ID	Device Serial Number Capability ID
14Ch	14Fh	DSN_LR	Serial Number Register (Lower DW)
150h	153h	DSN_UR	Serial Number Register (Upper DW)

[Table 78] Device Serial Number Capability Register Header

Bits	Type	Default Value	Description
31:20	RO	158h	Next Capability Offset
19:16	Hwlnit	1h	Capability Version
15:0	Hwlnit	3h	PCI Express Extended Capability ID

[Table 79] Serial Number Register Header (Lower DW)

Bits	Type	Default Value	Description
31:0	RO	0h	Serial Number register (Lower DW)

[Table 80] Serial Number Register Header (Upper DW)

Bits	Type	Default Value	Description
31:0	RO	0h	Serial Number register (Upper DW)

5.1.4.3 Power Budgeting Capability

[Table 81] Power Budgeting Capability Summary

Start Address	End Address	Symbol	Description
158h	15Bh	PB_ID	Power Budgeting Extended Capability ID
15Ch	15Fh	PB_SR	Data Select Register
160h	163h	PB_DR	Data Register
164h	167h	PB_BCR	Power Budget Capability Register

[Table 82] Power Budgeting Capability Header

Bits	Type	Default Value	Description
31:20	RO	168h	Next Capability Offset
19:16	RO	1h	Capability Version
15:00	RO	4h	PCI Express Extended Capability ID

[Table 83] Data Select Register

Bits	Type	Default Value	Description
31:8	RsvdP	0h	Reserved
7:0	RW	0h	Data Select

[Table 84] Data Register

Bits	Type	Default Value	Description
31:21	RsvdP	0h	Reserved
20:18	RO	0h	Power Rail
17:15	RO	0h	Type
14:13	RO	0h	PM State
12:10	RO	0h	PM Sub State
9:8	RO	0h	Data Scale
7:0	RO	0h	Base Power

[Table 85] Power Budget Capability Register

Bits	Type	Default Value	Description
7:1	RsvdP	0h	Reserved
0	Hwlnit	1h	System Allocated

5.1.4.4 Secondary PCI Express Capability

[Table 86] Secondary PCI Express Capability Summary

Start Address	End Address	Symbol	Description
168h	16Bh	SPE_ID	Secondary PCI Express Capability
16Ch	16Fh	PCIE_LC3	PCI Express Link Control 3
170h	173h	PCIE_LE	PCI Express Lane Error Status
174h	175h	PCIE_L0EC	PCI Express Lane 0 Equalization Control
176h	177h	PCIE_L1EC	PCI Express Lane 1 Equalization Control
178h	179h	PCIE_L2EC	PCI Express Lane 2 Equalization Control
17Ah	17Bh	PCIE_L3EC	PCI Express Lane 3 Equalization Control

[Table 87] Secondary PCI Express Capability ID Register

Bits	Type	Default Value	Description
31:20	RO	188h	Next Pointer
19:16	RO	1h	Capability Version
15:0	RO	19h	Capability ID (Secondary PCI Express Extended capability)

[Table 88] PCI Express Link Control 3 Register

Bits	Type	Default Value	Description
31:16	RsvdP	0h	Reserved
15:9	RW	0h	Enable Lower SKP OS Generation Vector (N/A)
8:2	RsvdP	0h	Reserved
1	RW	0	Link Equalization Request Interrupt Enable (N/A)
0	RW	0	Perform Equalization (N/A)

[Table 89] PCI Express Lane Error Status Register

Bits	Type	Default Value	Description
31:4	Rsvdp	0h	Reserved
3:0	RW1CS	0h	Lane Error Status Bits

[Table 90] Lane 0 Equalization Control Register

Bits	Type	Default Value	Description
15	RsvdP	0	Reserved
14:12	Hwlnit/RO	7h	Upstream Port 8.0T/s Receiver Preset Hint
11:8	Hwlnit/RO	Fh	Upstream Port 8.0T/s Transmitter Preset
7	RsvdP	0	Reserved
6:4	Hwlnit/RsvdP	0h	Downstream Port 8.0T/s Receiver Preset Hint (N/A)
3:0	Hwlnit/RsvdP	0h	Downstream Port 8.0T/s Transmitter Preset (N/A)

[Table 91] Lane 1 Equalization Control Register

Bits	Type	Default Value	Description
15	RsvdP	0	Reserved
14:12	Hwlnit/RO	7h	Upstream Port 8.0T/s Receiver Preset Hint
11:8	Hwlnit/RO	Fh	Upstream Port 8.0T/s Transmitter Preset
7	RsvdP	0	Reserved
6:4	Hwlnit/RsvdP	0h	Downstream Port 8.0T/s Receiver Preset Hint (N/A)
3:0	Hwlnit/RsvdP	0h	Downstream Port 8.0T/s Transmitter Preset (N/A)

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

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[Table 92] Lane 2 Equalization Control Register

Bits	Type	Default Value	Description
15	RsvdP	0	Reserved
14:12	Hwlnit/RO	7h	Upstream Port 8.0T/s Receiver Preset Hint
11:8	Hwlnit/RO	Fh	Upstream Port 8.0T/s Transmitter Preset
7	RsvdP	0	Reserved
6:4	Hwlnit/RsvdP	0h	Downstream Port 8.0T/s Receiver Preset Hint (N/A)
3:0	Hwlnit/RsvdP	0h	Downstream Port 8.0T/s Transmitter Preset (N/A)

[Table 93] Lane 3 Equalization Control Register

Bits	Type	Default Value	Description
15	RsvdP	0	Reserved
14:12	Hwlnit/RO	7h	Upstream Port 8.0T/s Receiver Preset Hint
11:8	Hwlnit/RO	Fh	Upstream Port 8.0T/s Transmitter Preset
7	RsvdP	0	Reserved
6:4	Hwlnit/RsvdP	0h	Downstream Port 8.0T/s Receiver Preset Hint (N/A)
3:0	Hwlnit/RsvdP	0h	Downstream Port 8.0T/s Transmitter Preset (N/A)

## 5.1.4.5 Latency Tolerance Reporting Capability Registers

[Table 94] Latency Tolerance Reporting Capability Summary

Start Address	End Address	Symbol	Description
188h	18Bh	LTR_ID	Latency Tolerance Reporting (LTR) Capability ID
18Ch	18Dh	LTR_SLR	LTR Max Snoop Latency Register
18Eh	18Fh	LTR_NSLR	LTR Max No-Snoop Latency Register

[Table 95] LTR Extended Capability Header

Bits	Type	Default Value	Description
31:20	RO	190h	Next Capability Offset
19:16	RO	1h	Capability Version
15:0	RO	18h	PCI Express Extended Capability ID

[Table 96] LTR Max Snoop latency Register

Bits	Type	Default Value	Description
15:13	RsvdP	0h	Reserved
12:10	RW	0h	Max Snoop latency Scale
9:0	RW	0h	Max Snoop latency Value

[Table 97] LTR Max No Snoop latency Register

Bits	Type	Default Value	Description
15:13	RsvdP	0h	Reserved
12:10	RW	0h	Max No Snoop Latency Scale
9:0	RW	0h	Max No Snoop Latency Value

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5.1.4.6 L1 Substates Extended Capability

[Table 98] L1 Substate Capability Summary

Start Address	End Address	Symbol	Description
190h	193h	L1S_CID	L1 Substate Capability ID
194h	197h	L1S_CR	L1 Substate Capability Register
198h	19Bh	L1S_C1R	L1 Substate Control 1 Register
19Ch	19Fh	L1S_C2R	L1 Substate Control 2 Register

[Table 99] L1 Substates Extended Capability Header

Bits	Type	Default Value	Description
31:20	RO	0	Next Capability Offset
19:16	RO	1h	Capability Version
15:0	RO	1Eh	PCI Express Extended Capability ID

[Table 100] L1 Substate Capability Register

Bits	Type	Default Value	Description
31:24	RsvdP	0h	Reserved
23:19	Hwlnit	5h	Port Power on value
18	RsvdP	0	Reserved
17:16	Hwlnit	0h	Port T_Power_on scale
15:8	Hwlnit	Ah	Port Common_mode_restore_time
7:5	RsvdP	0h	Reserved
4	Hwlnit	1	L1 PM Substates Supported
3	Hwlnit	1	ASPM PM L1.1 Supported
2	Hwlnit	1	ASPM PM L1.2 Supported
1	Hwlnit	1	PCI PM L1.1 Supported
0	Hwlnit	1	PCI PM L1.2 Supported

[Table 101] L1 Substate Control 1 Register

Bits	Type	Default Value	Description
31:29	RW	0h	LTR L1.2 Threshold Scale
28:26	RsvdP	0h	Reserved
25:16	RW	0h	LTR L1.2 Threshold value
15:8	RsvdP	0h	Common_mode_restore_time (N/A)
7:4	RsvdP	0h	Reserved
3	RW	0	ASPM PM L1.1 Supported
2	RW	0	ASPM PM L1.2 Supported
1	RW	0	PCI PM L1.1 Supported
0	RW	0	PCI PM L1.2 Supported

[Table 102] L1 Substate Control 2 Register

Bits	Type	Default Value	Description
31:8	RsvdP	0h	Reserved
7:3	RW	5h	T_POWER_ON Value
2	RsvdP	0	Reserved
1:0	RW	0h	T_POWER_ON Scale

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## 5.2 NVM Express Registers

### 5.2.1 Register Summary

[Table 103] Register Summary

Start Address	End Address	Name	Type
00h	07h	CAP	Controller Capabilities
08h	0Bh	VS	Version
0Ch	0Fh	INTMS	Interrupt Mask Set
10h	13h	INTMC	Interrupt Mask Clear
14h	17h	CC	Controller Configuration
18h	1Bh	Reserved	Reserved
1Ch	1Fh	CSTS	Controller Status
20h	23h	NSSR	NVM Subsystem Reset
24h	27h	AQA	Admin Queue Attributes
28h	2Fh	ASQ	Admin Submission Queue Base Address
30h	37h	ACQ	Admin Completion Queue Base Address
38h	3Bh	CMBLOC	Controller Memory Buffer Location (Optional)
3Ch	3Fh	CMBSZ	Controller Memory Buffer Size (Optional)
40h	EFFh	Reserved	Reserved
F00h	FFFh	Reserved	Command Set Specific
1000h	1003h	SQ0TCBL	Submission Queue 0 Tail Doorbell (Admin)
1000h + (1 * (4 << CAP.DSTRD))	1003h + (1 * (4 << CAP.DSTRD))	CQ0HDBL	Completion Queue 0 Head Doorbell (Admin)
...			
1000h + (2y * (4 << CAP.DSTRD))	1003h + (2y * (4 << CAP.DSTRD))	SQyTDVL	Submission Queue y Tail Doorbell
1000h + ((2y + 1) * (4 << CAP.DSTRD))	1003h + ((2y + 1) * (4 << CAP.DSTRD))	CQyHDBL	Completion Queue y Head Doorbell

### 5.2.2 Controller Registers

[Table 104] Controller Capabilities

Bits	Type	Name	Default Value	Description
63:56	RO		0h	Reserved
55:52	RO	MPSMAX	0h	Memory Page Size Maximum (Maximum is 4KB)
51:48	RO	MPSMIN	0	Memory Page Size Minimum (Minimum is 4KB)
47:45	RO		0	Reserved
44:37	RO	CSS	1h	Command Sets Supported
				1h: NVM command set
36	RO	NSSRS	1h	NVM Subsystem Reset Supported
35:32	RO	DSTRD	0	Doorbell Stride
				0: Stride of 4 bytes
31:24	RO	TO	3Ch	Timeout
				3Ch: 30 seconds
23:19	RO		0	Reserved
18:17	RO	AMS	1	Arbitration Mechanism Supported
				(Weighted Round Robin with Urgent supported)
16	RO	CQR	1	Contiguous Queues Required
15:00	RO	MQES	3FFFh	Maximum Queue Entries Supported
				(16384 entries supported)

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[Table 105] Version

Bits	Type	Name	Default Value	Description
31:16	RO	MJR	1h	Major Version Number
15:08	RO	MNR	2h	Minor Version Number
7:00	RO	Reserved	0	Reserved

**NOTE:**

Note: The PM981 supports NVM Express version 1.2

[Table 106] Interrupt Mask Set

Bits	Type	Name	Default Value	Description
31:00	RW1S	IVMS	0	Interrupt Vector Mask Set

[Table 107] Interrupt Mask Clear

Bits	Type	Name	Default Value	Description
31:00	RW1C	IVMC	0	Interrupt Vector Mask Clear

[Table 108] Controller Configuration

Bits	Type	Name	Default Value	Description
31:24	RO	-	0	Reserved
23:20	RW	IOCQES	0	I/O Completion Queue Entry Size (Configured as a power of 2) (Should be set to 4 for a 16 byte entry size)
19:16	RW	IOSQES	0	I/O Submission Queue Entry Size (Configured as a power of 2) (Should be set to 6 for a 64 byte entry size)
15:14	RW	SHN	0	Shutdown Notification 0h: No notification 1h: Normal shutdown notification 2h: Abrupt shutdown notification 3h: Reserved CSTS.SHST indicates shutdown status.
13:11	RW	AMS	0	Arbitration Mechanism Selected 0h: Round Robin No other values supported.
10:7	RW	MPS	0	Memory Page Size MPS is $2^{(12+MPS)}$ Shall be within CAP.MPSMAX and CAP.MPSMIN ranges.
6:4	RW	CSS	0	Command Set Selected 0h: NVM Command Set No other values supported
3:1	RO	-	0	Reserved
0	RW	EN	0	Enable When set to 1, controller shall process commands. When cleared to 0, controller shall not process commands. This field is subject to CSTS.RDY and CAP.TO restrictions.

**IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.**

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[Table 109] Controller Status

Bits	Type	Name	Default Value	Description
31:6	RO	-	0	Reserved
5	RW	PP	0	Processing Paused
4	RW1C	NSSRO	0	NVM Subsystem Reset Occurred
3:2	RO	SHST	0	Shutdown Status 0h: Normal operation, no shutdown requested 1h: Shutdown processing occurring 2h: Shutdown processing complete 3h: Reserved
1	RO	CFS	0	Controller Fatal Status
0	RO	RDY	0	1h: Controller ready to process commands 0h: Controller shall not process commands.

[Table 110] NVM Subsystem Reset

Bits	Type	Name	Default Value	Description
31:0	RW	NSSRC	0	NVM Subsystem Reset Control

[Table 111] Admin Queue Attributes

Bits	Type	Name	Default Value	Description
31:28	RO	-	0	Reserved
27:16	RW	ACQS	0	Admin Completion Queue Size Max: 4096 (Value of 4095h - 0's based value)
15:12	RO	-	0	Reserved
11:0	RW	ASQS	0	Admin Submission Queue Size Max: 4096 (Value of 4095h - 0's based value)

[Table 112] Admin Submission Queue Base Address

Bits	Type	Name	Default Value	Description
63:12	RW	ASQB	0	Admin Submission Queue Base Address
11:0	RO	-	0	Reserved

[Table 113] Admin Completion Queue Base Address

Bits	Type	Name	Default Value	Description
63:12	RW	ACQB	0	Admin Completion Queue Base Address
11:0	RO	-	0	Reserved

[Table 114] Controller Memory Buffer Location

Bits	Type	Name	Default Value	Description
31:12	RO	OFST	0	Offset
11:3	RO	-	0	Reserved
2:0	RO	BIR	0	Base Indicator Register

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[Table 115] Controller Memory Buffer Size

Bits	Type	Name	Default Value	Description
31:12	RO	SZ	0	Size
11:8	RO	SZU	0	Size Units
7:5	RO		0	Reserved
4	RO	WDS	0	Write Data Support
3	RO	RDS	0	Read Data Support
2	RO	LISTS	0	PRP SGL List Support
1	RO	CQS	0	Completion Queue Support
0	RO	SQS	0	Submission Queue Support

[Table 116] Submission Queue Tail y Doorbell

Bits	Type	Name	Default Value	Description
31:16	RO		0	Reserved
15:0	RW	SQT	0	Submission Queue Tail

[Table 117] Completion Queue Head y Doorbell

Bits	Type	Name	Default Value	Description
31:16	RO		0	Reserved
15:0	RW	CQH	0	Completion Queue Head

## 6.0 Supported Command Set

The Admin command sets and NVM I/O command sets of Samsung SSD PM981 are defined in compliant with NVM Express specification revision 1.2.

### 6.1 Admin Command Set

The Admin command set is the commands that are submitted to the Admin Submission Queues. The detailed specifications are described in NVM Express specification document.

[Table 118] Opcode for Admin Commands

Opcode (Hex)	Command Name
00h	Delete I/O Submission Queue
01h	Create I/O Submission Queue
02h	Get Log Page
04h	Delete I/O Completion Queue
05h	Create I/O Completion Queue
06h	Identify
08h	Abort
09h	Set Feature
0Ah	Get Feature
0Ch	Asynchronous Event Request
10h	Firmware Activate
11h	Firmware Image Download
14h	Device Self-test
80h	Format NVM
81h	Security Send
82h	Security Receive
C0h – FFh	Vendor Specific

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## 6.1.1 Identify Command

The Identify Command returns the data described below.

[Table 119] Identify Controller Data Structure

Bytes	O/M	Default Value	Description
1:0	M	144Dh	PCI Vendor ID
3:2	M	144Dh	PCI Subsystem Vendor ID
23:4	M	S###N#####	Serial Number (ASCII), #:Variables
63:24	M	256GB: SAMSUNG MZVLB256HAHQ-00000/07 512GB: SAMSUNG MZVLB512HAJQ-00000/07 1024GB: SAMSUNG MZVLB1T0HALR-00000/07 2048GB: SAMSUNG MZVLB2T0HMLB-00000/07	Model Number (ASCII)
71:64	M	EX#####	Firmware Revision, #:Variables
72	M	2h	Recommended Arbitration Burst
75:73	M	002538h	IEEE OUI
76	O	0	Controller Multi-Path I/O and Namespace Sharing Capabilities Bit 2: 1h - Controller is associated with an SR-IOV Virtual Function 0h - Controller is associated with a PCI Function. Bit 1: 1h - Device has Two or More controller 0h - Device has One Controller Bit 0: 1h - Device has Two or More physical PCI Express ports 0h - Device has One PCI Express port
77	M	9h	Maximum Data Transfer Size 0h: No restrictions on transfer size
79:78	M	4h	Controller ID (CNTLID)
83:80	M	00010200h	Version
87:84	M	000186A0h	RTD3 Resume Latency
91:88	M	007A1200h	RTD3 Entry Latency
95:92	M	0h	Optional Asynchronous Events Supported
255:96	M	0h	Reserved
257:256	M	17h	Optional Admin Command Support Bits 15:5 - Reserved Bit 4: 1h - Device Self-Test Bit 3: 0h - Namespace Management Attachment Not Supported Bit 2: 1h - Firmware Activate/Download Supported Bit 1: 1h Format NVM Supported Bit 0: 1h Security Send and Security Receive Supported
258	M	7h	Abort Command Limit (Maximum number of concurrently outstanding Abort commands) (0's based value)
259	M	3h	Asynchronous Event Request Limit (Maximum number of concurrently outstanding Asynchronous Event Request commands) (0's based value)
260	M	16h	Firmware Updates Bits 7:5 - Reserved Bit 4 - 1h Support firmware activation without a reset Bits 3:1 - Number of firmware slots Bit 0 - 0h, "1" indicates Slot 1 is read only
261	M	3h	Log Page Attributes Bits 7:1 - Reserved Bit 0: 0h SMART data is global for all namespaces
262	M	3Fh	Error Log Page Entries (Number of Error Information log entries stored by controller) (0's based value)

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263	M	4h	Number of Power States Support (0's based value)
264	M	1h	Admin Vendor Specific Command Configuration Bits 7:1 – reserved Bit 0 – Indicates Admin Vendor Specific Commands use the format defined in NVM Express 1.0c Figure 8.
265	O	1h	Autonomous Power State Transition Attributes (APSTA)
267:266	M	256GB/512GB/1TB: 0x162 2TB: 0x161	Warning Composite Temperature Threshold
269:268	M	256GB/512GB/1TB: 0x163 2TB: 0x162	Critical Composite Temperature Threshold
271:270	O	0h	Maximum Time for Firmware Activation
275:272	O	0h	Host Memory Buffer Preferred Size
279:276	O	0h	Host Memory Buffer Minimum Size
295:280	O	2048GB: 1DCEE56000h	Total NVM Capacity
		1024GB: EE77A56000h	
		512GB: 773C256000h	
		256GB: 3B9E656000h	
311:296	O	0h	Unallocated NVM Capacity
315:312	O	0h	Replay Protected Memory Block Support
317:316	O	23h	Extended Device Self-Test Time
318	O	0h	Device Self-Test Options
511:316		-	Reserved
512	M	66h	Submission Queue Entry Size Bits 7:4 – 6h Max SQES (64 bytes) Bits 3:0 – 6h Required SQES (64 bytes)
513	M	44h	Completion Queue Entry Size Bits 7:4 – 4h Max CQES (16 bytes) Bits 3:0 – 4h Required CQES (16 bytes)
515:514		0	Reserved
519:516	M	1h	Number of Namespaces
521:520	M	1Fh	Optional NVM Command Support Bits 15:6 – Reserved Bit 5 – 1h Reservations Supported 0h Not support Reservations Bit 4 – 1h Save field in Set Feature & Select field in Get Feature Supported 0h Not support Save field in Set Feature & Select field in Get Feature Bit 3 – 1h Write Zeros Supported 0h Not support Write Zeros Bit 2 – 1h Dataset Management Supported 0h Not support Dataset Management Bit 1 – 1h Write Uncorrectable Supported 0h Not support Write Uncorrectable Bit 0 – 1h Compare Supported 0h Not support Compare
523:522	M	0h	Fused Operation Support Bits 15:1 – Reserved Bit 0 – 0h Compare/Write Fused Operation Not Supported

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524	M	0h for Non-SED 4h for SED	Format NVM Attributes Bits 7:3 – Reserved Bit 2 – 1h Cryptographic Erase is supported 0h Cryptographic Erase is not supported Bit 1 – 0h Cryptographic erase and user data erase Per Namespace Bit 0 – 0h Format Per Namespace
525	M	1h	Volatile Write Cache Bits 7:1 - Reserved Bit 0 -1h Volatile write cache is present 0h No Volatile Write Cache present
527:526	M	3FFh	Atomic Write Unit Normal (0's based value)
529:528	M	0h	Atomic Write Unit Power Fail (0's based value)
530	M	1h	NVM Vendor Specific Command Configuration Bits 7:1 – reserved Bit 0 – Indicates NVM Vendor Specific Commands use the format defined in NVM Express
531	M	0h	Reserved
533:532	O	0h	ACWU
534:533	M	0h	Reserved
539:536	O	0h	No SGL support
703:540	-	0h	Reserved
I/O Command Set Attributes			
2047:704	-	0h	Reserved
Power State Descriptors			
2079:2048	M	refer to 'Identify Power State Descriptor Data Structure'	Power State 0 Descriptor
2111:2080	O	refer to 'Identify Power State Descriptor Data Structure'	Power State 1 Descriptor
2143:2112	O	refer to 'Identify Power State Descriptor Data Structure'	Power State 2 Descriptor
2175:2144	O	refer to 'Identify Power State Descriptor Data Structure'	Power State 3 Descriptor
2207:2176	O	refer to 'Identify Power State Descriptor Data Structure'	Power State 4 Descriptor
...	-	0h	(N/A)
3071:3040	O	0h	Power State 31 Descriptor (N/A)
Vendor Specific			
3278:3072	-	Samsung Specific	Samsung Reserved
3279	O	5h for Non-SED 7h for SED	Security Feature Set Bit 2 – 1h TCG Supported Bit 1 – 1h SED Supported Bit 0 – 1h ATA Security Supported
4095:3280	-	0h	Samsung Reserved

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[Table 120] Identify Power State Descriptor Data Structure

Bytes	Description	Power State 0 Descriptor	Power State 1 Descriptor	Power State 2 Descriptor	Power State 3 Descriptor	Power State 4 Descriptor
255:184	Reserved					
183:182	Active Power Scale(APS)	0h	0h	0h	0h	0h
181:179	Reserved					
178:176	Active Power Workload(APW)	0h	0h	0h	0h	0h
175:160	Active Power(ACTP)	0h	0h	0h	0h	0h
159:152	Reserved					
151:150	Idle Power Scale(IPS)	0h	0h	0h	0h	0h
149:144	Reserved					
143:128	Idle Power(IDLP)	0h	0h	0h	0h	0h
127:125	Reserved					
124:120	Relative Write Latency	0h	1h	2h	3h	4h
119:117	Reserved					
116:112	Relative Write Throughput	0h	1h	2h	3h	4h
111:109	Reserved					
108:104	Relative Read Latency	0h	1h	2h	3h	4h
103:101	Reserved					
100:96	Relative Read Throughput	0h	1h	2h	3h	4h
95:64	Exit Latency	0h	0h	0h	4B0h	1F40h
63:32	Entry Latency	0h	0h	0h	D2h	7D0h
31:26	Reserved					
25	Non-Operational State	0h	0h	0h	1h	1h
24	Max Power Scale	0h	0h	0h	1h	1h
23:16	Reserved					
15:00	Maximum Power	2BEh	276h	15Eh	2F8h	32h

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[Table 121] Identify Namespace Data Structure

Bytes	O/M	Default Value		Description
7:0	M	2048GB	EE7752B0h	Namespace Size
		1024GB	773BD2B0h	
		512GB	3B9E12B0h	
		256GB	1DCF32B0h	
15:8	M	2048GB	EE7752B0h	Namespace Capacity
		1024GB	773BD2B0h	
		512GB	3B9E12B0h	
		256GB	1DCF32B0h	
23:16	M	2048GB	0	Namespace Utilization
		1024GB	0	
		512GB	0	
		256GB	0	
24	M	0h		Namespace Features Bits 7:1 Reserved Bit 0: 0h Thin provisioning not supported
25	M	0h		Number of LBA Formats
26	M	0h		Formatted LBA Size Bits 7:5 – Reserved Bit 4: Metadata interleaved or separate (based on LBA format) Bit 3:0 – Indicates LBA format
27	M	0h		Metadata Capabilities Bits 7:2 – Reserved Bit 1 – Supports Metadata as separate buffer Bit 0 – Supports Metadata as extended LBA
28	M	0h		End-to-end Data Protection Capabilities Bits 7:5 – Reserved Bit 4 – Supports protection information as last 8 bytes of Metadata Bit 3 – Supports protection information as first 8 bytes of metadata Bit 2 – Supports Type 3 protection information Bit 1 – Supports Type 2 protection information Bit 0 – Supports Type 1 protection information
29	M	0h		End-to-End Data Protection Type Settings Bits 7:4 – Reserved Bit 3 – 1: Protection information transferred as first 8 bytes of metadata Bit 3 – 0: Protection information transferred as last 8 bytes of metadata Bit 2:0 – 000b: Protection information disabled Bit 2:0 – 1h: Protection type 1 enabled Bit 2:0 – 2h: Protection type 2 enabled Bit 2:0 – 3h: Protection type 3 enabled
30	O	0h		Namespace Multi-path I/O and Namespace sharing Capabilities (NMIC) Bits 7:1 - Reserved Bit 0 - 1 : Accessible by two or more controllers Bit 0 - 0 : Private namespace

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31	O	0h	Reservation Capabilities (RESCAP) Bits 7 - Reserved Bits 6 - 1 : Namespace supports the Exclusive Access (All Registrants reservation type) Bit 5 - 1 : Namespace supports the Write Exclusive (All Registrants reservation type) Bit 4 - 1 : Namespace supports the Exclusive Access (Registrants only reservation type) Bit 3 - 1 : Namespace supports the Write Exclusive (Registrants only reservation type) Bit 2 - 1 : Namespace supports the Exclusive Access Reservation type Bit 1 - 1 : Namespace supports the Write Exclusive Reservation type Bit 0 - 1 : Namespace supports the Persist Through Power Loss capability
32	O	80h	Bit 7 - 1:Format Progress Indicator
33		-	Reserved
35:34	O	0h	Namespace Atomic Write Unit Normal
37:36	O	0h	Namespace Atomic Write Unit Power Fail
39:38	O	0h	Namespzcce Atomic Compare & Write Unit
41:40	O	0h	Namespace Atomic Boundary Size Normal
43:42	O	0h	Namespace Atomic Boundary Offset
45:44	O	0h	Namespace Atomic Boundary Size Power Fail
47:46		-	Reserved
63:48	O	2048GB	1DCEEA56000h
		1024GB	EE77A56000h
		512GB	773C256000h
		256GB	3B9E656000h
			NVM Capacity
103:64		-	Reserved
119:104	O	0h	Namespace Globally Unique Identifier (NGUID) #:Variables *NGUID specifies data in a big endian format.
127:120	O	002538#####h	IEEE Extended Unique Identifier(EUI64) #:Variables *EUI64 specifies data in a big endian format.
131:128	M	refer to 'LBA Format 0 Data Structure'	LBA Format 0 Support
135:132	O	0h	LBA Format 1 Support
139:136	O	0h	LBA Format 2 Support
143:140	O	0h	LBA Format 3 Support
147:144	O	0h	LBA Format 4 Support (N/A)
...			
191:188	O	0h	LBA Format 15 Support (N/A)
383:192	-	0h	Reserved
Vendor Specific			
4095:384	-	0h	Samsung Reserved

**IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.**



[Table 122] LBA Format 0 Data Structure

Bits	Name	Default Value	Description
31:26	-	0	Reserved
25:24	RP	0	Relative Performance
23:16	LBADS	9h	LBA Data Size
15:00	MS	0	Meta data Size

## 6.2 NVM Express I/O Command Set

[Table 123] Opcode for NVM Express I/O Commands

Opcode (Hex)	Command Name
00h	Flush
01h	Write
02h	Read
04h	Write Uncorrectable
05h	Compare
08h	Write Zeroes
09h	Dataset Management

**NOTE:**

1) Deallocate feature in Dataset Management command is only supported in the Samsung SSD PM981.

### 6.3 SMART/Health Information

[Table 124] SMART/Health Information Log

Bytes	Default Value	Attribute Description
0	0	Critical Warning Bit 7:5 – Reserved Bit 4 – 1h: the volatile memory backup device has failed. (only valid if the controller has a volatile memory backup solution) Bit 3 – 1h: the media has been placed in read only mode Bit 2 – 1h: the NVM subsystem reliability has been degraded due to significant media related errors or any internal error that degrades NVM subsystem reliability Bit 1 – 1h: a temperature is above an over temperature threshold or below an under temperature threshold Bit 0 – 1h: the available spare space has fallen below the threshold
2:1	current temp	Temperature
3	100	Available Spare
4	10	Available Spare Threshold
5	0	Percentage Used
31:6	-	Reserved
47:32	0	Data Units Read
63:48	0	Data Units Written
79:64	0	Host Read Commands
95:80	0	Host Write Commands
111:96	0	Controller Busy Time
127:112	0	Power Cycles
143:128	0	Power On Hours
159:144	0	Unsafe Shutdowns
175:160	0	Media and Data Integrity Errors
191:176	0	Number of Error Information Log Entries
195:192	0	Warning Composite Temperature Time
199:196	0	Critical Composite Temperature Time
201:200	current temp.	Temperature Sensor 1
203:202	current temp.	Temperature Sensor 2
205:204	0	Temperature Sensor 3
207:206	0	Temperature Sensor 4
209:208	0	Temperature Sensor 5
211:210	0	Temperature Sensor 6
213:212	0	Temperature Sensor 7
215:213	0	Temperature Sensor 8
511:216	-	Reserved

## 7.0 PRODUCT COMPLIANCE

### 7.1 Product regulatory compliance and Certifications

[Table 125] Certifications and Declarations

Category	Certifications
Safety	c-UL-us
	CE
	TUV
	CB
EMC	CE (EU)
	BSMI (Taiwan)
	KCC (South Korea)
	VCCI (Japan)
	RCM (Australia)
	FCC (USA)
	IC (CANADA)

The three existing compliance marks (C-Tick, A-Tick and RCM) are consolidated into a single compliance mark - the RCM.



Caution: Any changes or modifications in construction of this device which are not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

**NOTE:** This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Modifications not expressly approved by the manufacturer could void the user's authority to operated the equipment under FCC rules.



Industry Canada ICES-003 Compliance Label:

CAN ICES-3 (B)/NMB-3(B)

**IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.**

## 8.0 References

[Table 126] Standards References

Item	Website
PCI Express Base Specification Revision 3.0	<a href="http://www.pcisig.com/specifications/pciexpress/base3/">http://www.pcisig.com/specifications/pciexpress/base3/</a>
PCI Express M.2 Specification Revision 1.1	<a href="http://pcisig.com/specifications">http://pcisig.com/specifications</a>
NVM Express Specification Rev. 1.2	<a href="http://www.nvmexpress.org/">http://www.nvmexpress.org/</a>
Solid-State Drive Requirements and Endurance Test Method (JESD218A)	<a href="http://www.jedec.org/standards-documents/docs/jesd218a">http://www.jedec.org/standards-documents/docs/jesd218a</a>
Solid-State Drive Requirements and Endurance Test Method (JESD219A)	<a href="http://www.jedec.org/standards-documents/docs/jesd219a">http://www.jedec.org/standards-documents/docs/jesd219a</a>